

## Class-AB Speaker Amplifiers

## 1.1W to 1.5W

## Monaural Speaker Amplifier



BD7830NUV

No.10077EAT03

**●Description**

The BD7830NUV is a monaural speaker amplifier that operates at low voltage and was developed for portable navigation and mobile audio products. When in standby mode, its current consumption is 0  $\mu$ A, and since it switches quickly and quietly from standby to ON, it is especially well suited for applications where there is frequent switching between standby and ON.

**●Features**

- 1) BTL monaural audio power amplifier
- 2) High power 2.25W 4 $\Omega$  at  $V_{CC}=5V$  ,THD+N=10%  
 High power 1.55W 8 $\Omega$  at  $V_{CC}=5V$  ,THD+N=10%  
 High power 0.77W 8 $\Omega$  at  $V_{CC}=3.6V$  ,THD+N=10%
- 3) Wide operating supply voltage range: 2.4~5.5V
- 4) Low standby current: 0 $\mu$ A
- 5) Fast turn on/off time: 46msec
- 6) Built-in Fade-in/out function
- 7) Built-in anti-pop function
- 8) Built-in thermal shutdown function
- 9) Very small package (VSON008V2030)

**●Applications**

Mobile phones, Mobile electronics applications

**●Absolute Maximum Ratings(Ta=+25°C)**

Parameter	Symbol	Ratings	Unit
Supply voltage	$V_{CC}$	6.0	V
Power dissipation	$P_d$	530 <sup>*1</sup>	mW
Storage temperature range	$T_{stg}$	-55~+150	°C
STBY input range	$V_{STBY}$	-0.1~ $V_{CC}+0.1$	V

\*1 ROHM standard one layer board (70mm × 70mm × 1.6mm) mounted, deratings is done at 4.24mW/°C above Ta=+25°C.

**●Operating Range**

Parameter	Symbol	Ratings	Unit
Temperature range	$T_{opr}$	-40~+85	°C
Supply voltage	$V_{CC}$	+2.4~+5.5	V

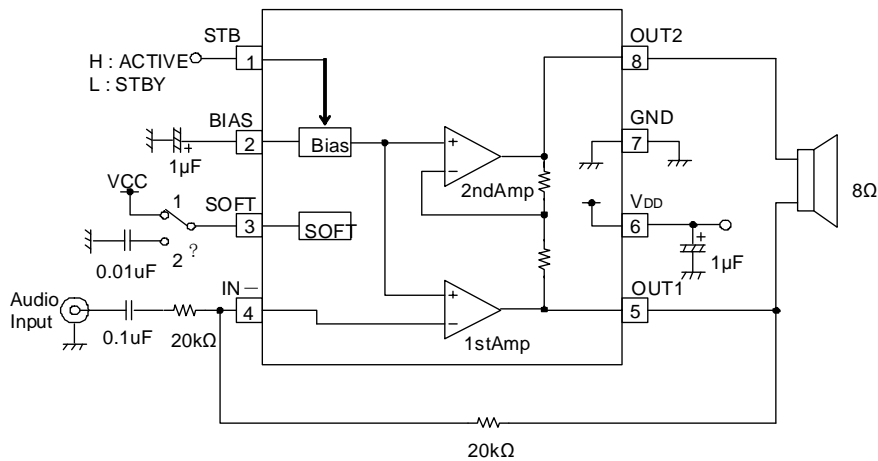
※ This product is not designed for protection against radioactive rays.

●Electrical characteristics (Unless otherwise noted, Ta=+25°C, V<sub>CC</sub>=+3.0V, f=1kHz, R<sub>L</sub>=8Ω)

Parameter	Symbol	Limit			Unit	Monitor pin	Condition
		MIN.	TYP.	MAX.			
Supply current	I <sub>CC</sub>	—	3.2	6.8	mA	6	Active mode
Standby supply current	I <sub>STBY</sub>	—	0	2	μA	6	Standby mode
Output power	P <sub>O</sub>	280	420	—	mW	5&8	BTL, THD+N=1% <sup>*1</sup>
Total harmonic distortion	THD+N	—	0.1	0.5	%	5&8	BTL, P <sub>o</sub> =150mW <sup>*1</sup>
Voltage gain1	A <sub>V1</sub>	-1	0	+1	dB	5	V <sub>in</sub> =-20dBV, 1stAmp
Voltage gain2	A <sub>V2</sub>	-1	0	+1	dB	8	V <sub>in</sub> =-20dBV, 2ndAmp
Power supply rejection ratio	PSRR	40	57	—	dB	5&8	BTL, V <sub>ripple</sub> =0.2V <sub>pp</sub> <sup>*2</sup>
Mute attenuation	MUTE	60	80	—	dB	5&8	BTL, V <sub>in</sub> =-20dBV
Output voltage	V <sub>o</sub>	1.35	1.5	1.65	V	5&8	V <sub>in</sub> =0V
Output offset voltage	ΔV <sub>o</sub>	-40	0	+40	mV	5&8	ΔV <sub>o</sub> = V <sub>o1</sub> -V <sub>o2</sub>
STBY release voltage	V <sub>STBYH</sub>	1.4	—	V <sub>CC</sub> +0.1	V	1	Active mode
STBY hold voltage	V <sub>STBYL</sub>	-0.1	—	0.4	V	1	Standby mode
STBY input current H	I <sub>STBYH</sub>	20	30	40	μA	1	V <sub>STBY</sub> =3V
STBY input current L	I <sub>STBYL</sub>	-2	0	—	μA	1	V <sub>STBY</sub> =0V

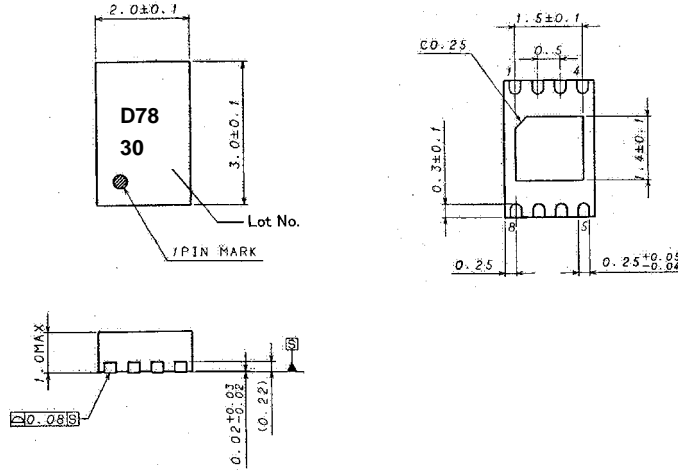
\*1:B.W.=400~30kHz, \*2:DIN AUDIO, SE:Single End, BTL:The voltage between 5pin and 8pin

●Application Circuit Example

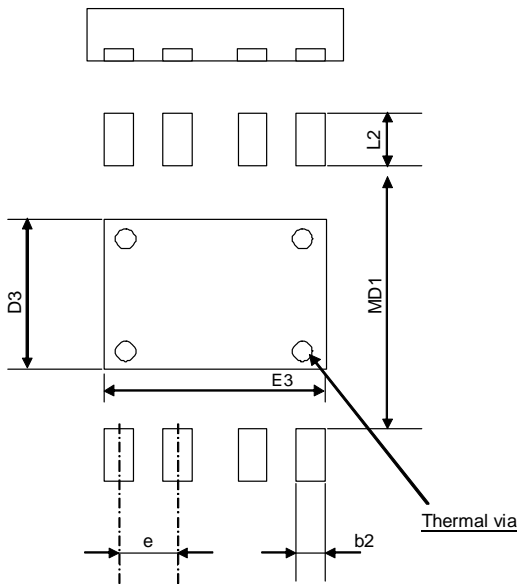


※3pin SOFT terminal  
 1 : Usually  
 2 : Enable to adjust fade in/out time by external capacitor

●Outer dimension



●Reference land pattern (adapt as necessary to suit conditions during actual design.)



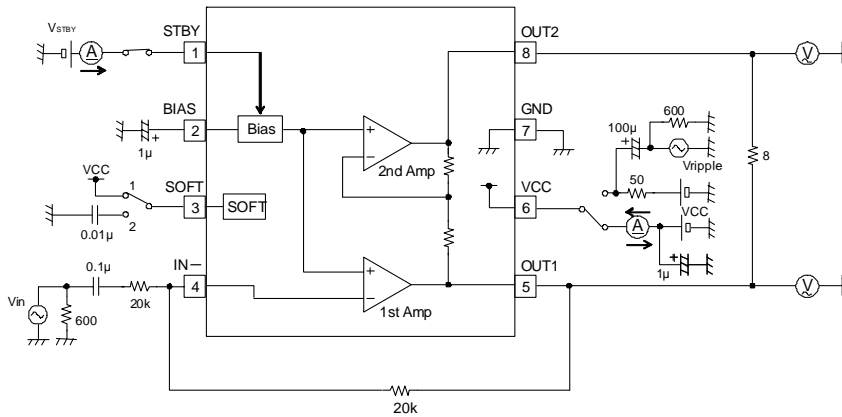
Unit: mm

PKG type	Lead pitch e	Land		
		Gap MD1	Length L2	Width b2
VSON008V2030	0.50	2.20	0.70	0.27

PKG type	Central pad		Thermal via	
	Length D3	Width E3	Pitch	Diameter
VSON008V2030	1.20	1.60	—	φ 0.300

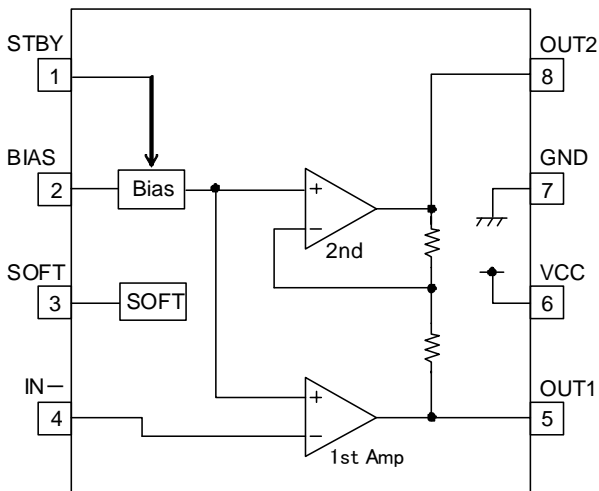
※ This package is a non-lead type, so solderability of the lead ends and sides are not guaranteed.

● Measurement Circuit Diagram



- ※3pin SOFT terminal  
 1: Usually  
 2: Enable to adjust fade in/out time by external capacitor

● Block diagram



● Pin assignment

PIN No.	PIN Name
1	STBY
2	BIAS
3	SOFT
4	IN-
5	OUT1
6	VCC
7	GND
8	OUT2

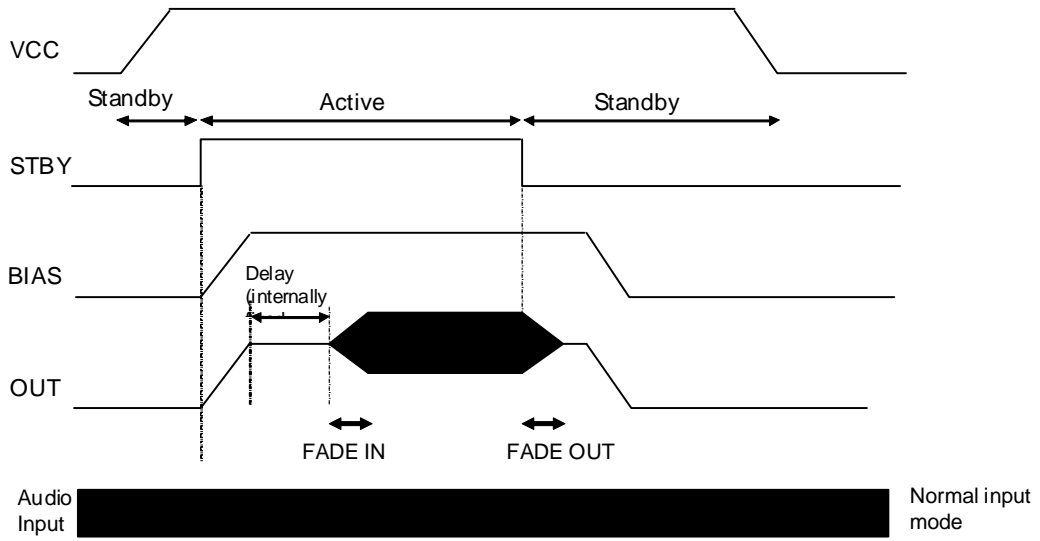
●Input/output equivalent circuit

PIN No.	PIN Name	PIN description	Equivalent circuit
1	STBY	Active/Standby Control pin STBY=H → Active STBY=L → Standby	
2	BIAS	Bias capacitor Connection pin	
3	SOFT	Fade-in/out Adjustment pin	
4	IN-	Input pin	
5 8	OUT1 OUT2	Output pin	
6	VCC	Power supply pin	
7	GND	GND pin	

Notes) The above numerical values are typical values for the design, which are not guaranteed.

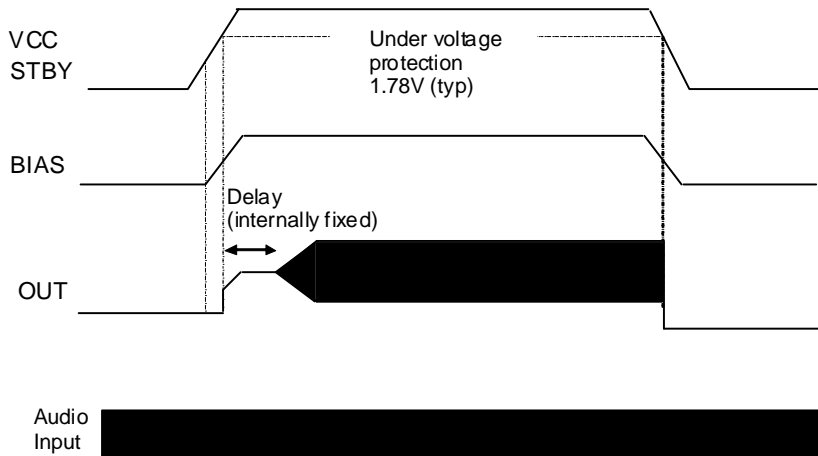
●Description of operations

①ON/OFF operation by STBY pin



Once VCC = H, when STBY = L → H then BIAS and output (OUT) are activated.  
 Once BIAS has become stable (= 1/2 VCC), output (OUT) fades in (FADE IN).  
 Once STBY = H → L, output (OUT) starts to fade out (FADE OUT), and when fade-out ends, the BIAS falls.

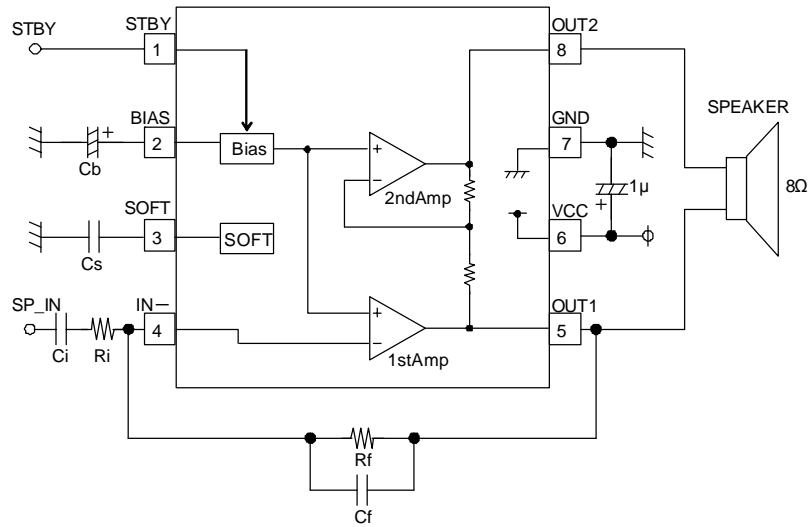
②ON/OFF control by shorting of VCC and STBY pins



When VCC = STBY = L → H, BIAS is activated. During low power mode (VCC < 1.78 V) protection is used to keep output (OUT) at low level, and FADE IN occurs when this protection is canceled. When VCC = STBY = H → L, output (OUT) falls without FADE OUT.

●External components and cautions points

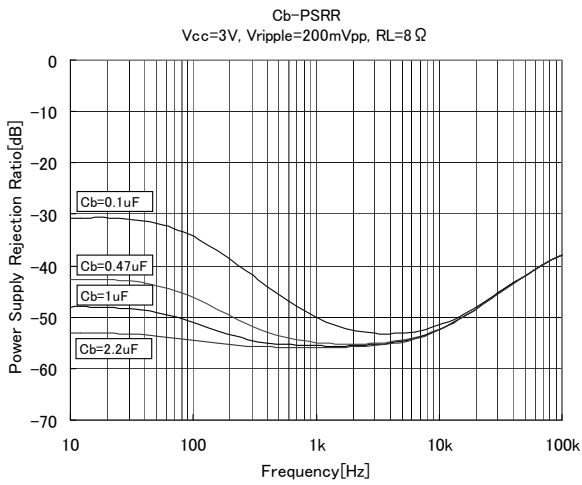
Setting of external components



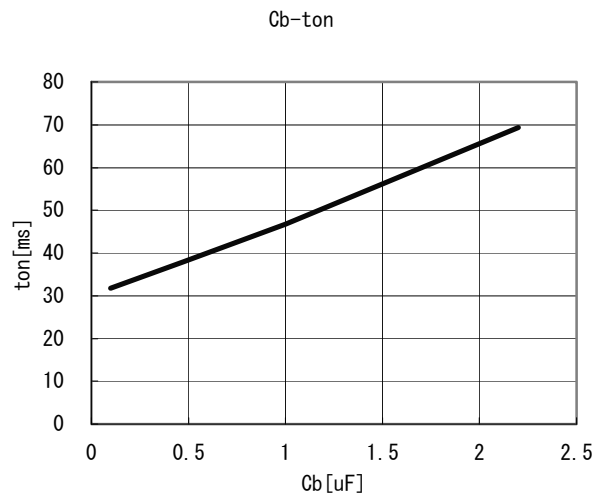
●Cb

This is a bypass capacitor, which is used for bias voltage stabilization. When a larger capacitor is used, the efficiency of voltage ripple rejection can be improved. When tuning, note with caution that  $C_b$  can affect the activation time.

Cb – Power Supply Ripple Rejection Ratio



Cb – Turn-on Time

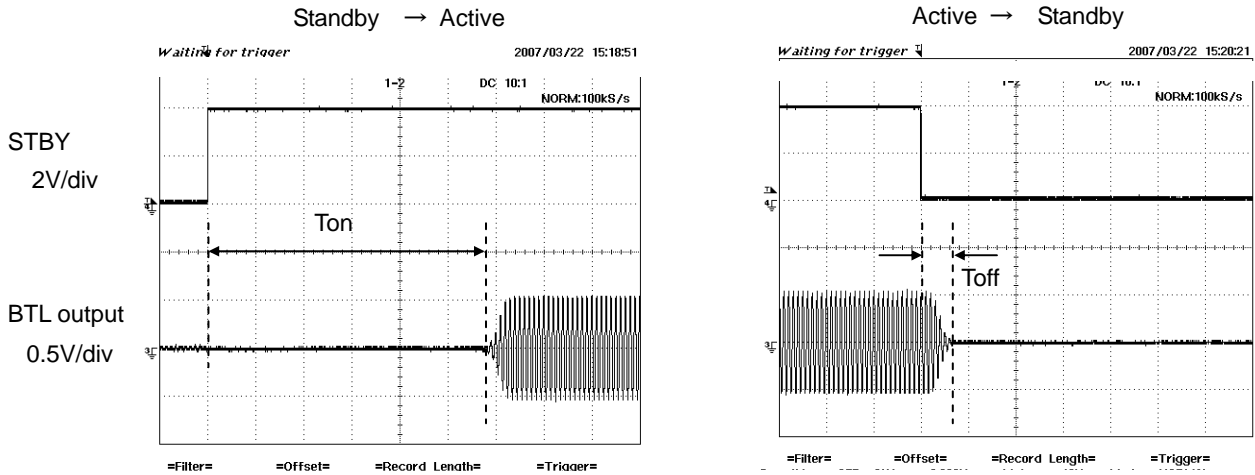


●Cs

This capacitor is for adjustment of the FADE IN/OUT times. The FADE IN/OUT functions soften the operation (IN and OUT) of BTL output when switching between standby and active modes.

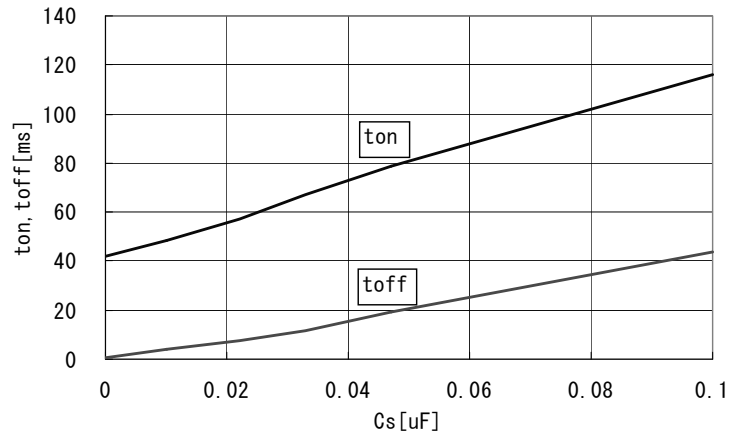
When a capacitor is connected to the SOFT pin (pin 3), the FADE IN/OUT functions are valid. When the capacitor rating is increased, the FADE IN/OUT effect is also increased, but note with caution when setting this that it also affects the activation time. If the FADE IN/OUT functions are not being used, connect the SOFT pin (pin 3) to VCC.

- Fade-in/out waveforms



Cs - Fade-in/out Time

Cs-ton, toff





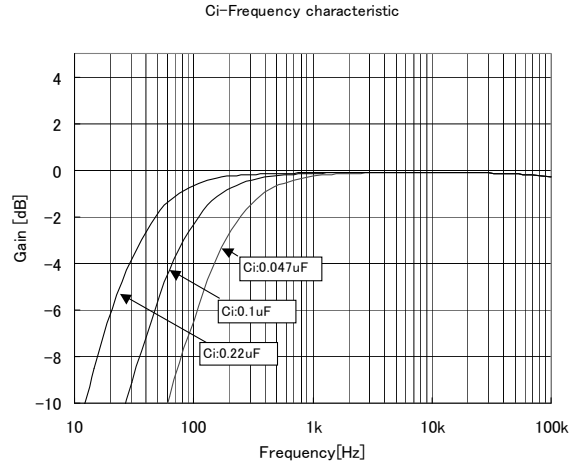
● **Ci**

This is a DC cut-off input coupling capacitor for the amp input pin.

This includes an Ri and a high-pass filter. The cut-off frequency is calculated as follows.

$$f_{CL} = \frac{1}{2\pi \times R_i \times C_i} \quad [\text{Hz}]$$

Ci – Low Frequency Characteristics



Capacitors of a certain size are required for coupling without attenuation of low frequencies, but in most cases of speakers used in portable equipment, it is nearly impossible to reproduce signals in the 100 to 200 Hz range or below. Even when a larger capacitor is used instead, it may not improve system performance. Also, pop sounds can affect the capacitance (Ci) of the capacitor. A larger coupling capacitor requires a greater charge to reach the bias DC voltage (normally 1/2 VCC). Because this charge current is supplied from the output due to routing of feedback, pop sounds occur easily at startup. Consequently, pop sounds can be minimized by selecting the smallest capacitor that still has the required low-frequency response.

● **Ri**

This is inverting input resistance, which sets the closed loop gain in conjunction with Rf.

● **Rf**

This is feedback resistance, which sets closed loop gain in conjunction with Rf. The amp gain is set using the following formula.

$$\text{Gain} = 20 \log \left( \frac{R_f}{R_i} \right) \quad [\text{dB}]$$

● **Cf**

This is a feedback capacitor, which is used to cut high frequencies.

This includes Rf and a low-pass filter. The cut-off frequency is calculated as follows.

$$f_{CL} = \frac{1}{2\pi \times R_i \times C_i} \quad [\text{Hz}]$$

### ● Selection of external components

#### ① Setting gain from desired output

Output  $P_o$  is determined via the following formula, from which the required gain  $A_v$  can also be obtained.

$$P_o [\text{W}] = V_o^2 [\text{V}_{\text{rms}}] / R_L [\Omega]$$

$$V_o = A_v \cdot V_{\text{in}}$$

$$A_v \geq \sqrt{P_o \cdot R_L} / V_{\text{in}}$$

#### ② Setting input resistance and feedback resistance from gain

Gain  $A_v$  is determined via the following formula, from which input resistance  $R_{\text{in}}$  and feedback resistance  $R_f$  can be set.

$$A_v = (R_f / R_{\text{in}}) \cdot 2$$

$R_{\text{in}}$  is set with the input side's drive capacity taken into account.

#### ③ Setting input coupling capacitor from low-range cut-off frequency

Low-range cut-off frequency  $f_c$  is determined via the following formula, from which input coupling capacitor  $C_{\text{in}}$  can be set.

$$f_c [\text{Hz}] = 1 / (2\pi \cdot R_{\text{in}} \cdot C_{\text{in}})$$

$$C_{\text{in}} \geq 1 / (2\pi \cdot R_{\text{in}} \cdot f_c)$$

#### ④ Setting bias capacitor and SOFT capacitor to minimize pops

It is recommended that the capacitance of the bias capacitor  $C_B$  be set to at least 10 times that of the input coupling capacitor  $C_{\text{in}}$ , in order to soften the rise of the bias voltage while improving the  $C_{\text{in}}$  following ability.

Also, when a higher gain is used, the capacitance of the SOFT capacitor  $C_s$  can be raised to control pop sounds.

$$A_v = 2 \text{ (6 dB at BTL)} \rightarrow C_s \cdot (80 / f_c) \geq 0.01 \mu\text{F}$$

$$A_v = 4 \text{ (12 dB at BTL)} \rightarrow C_s \cdot (80 / f_c) \geq 0.022 \mu\text{F}$$

$$A_v = 8 \text{ (18 dB at BTL)} \rightarrow C_s \cdot (80 / f_c) \geq 0.033 \mu\text{F}$$

$$A_v = 20 \text{ (26 dB at BTL)} \rightarrow C_s \cdot (80 / f_c) \geq 0.068 \mu\text{F}$$

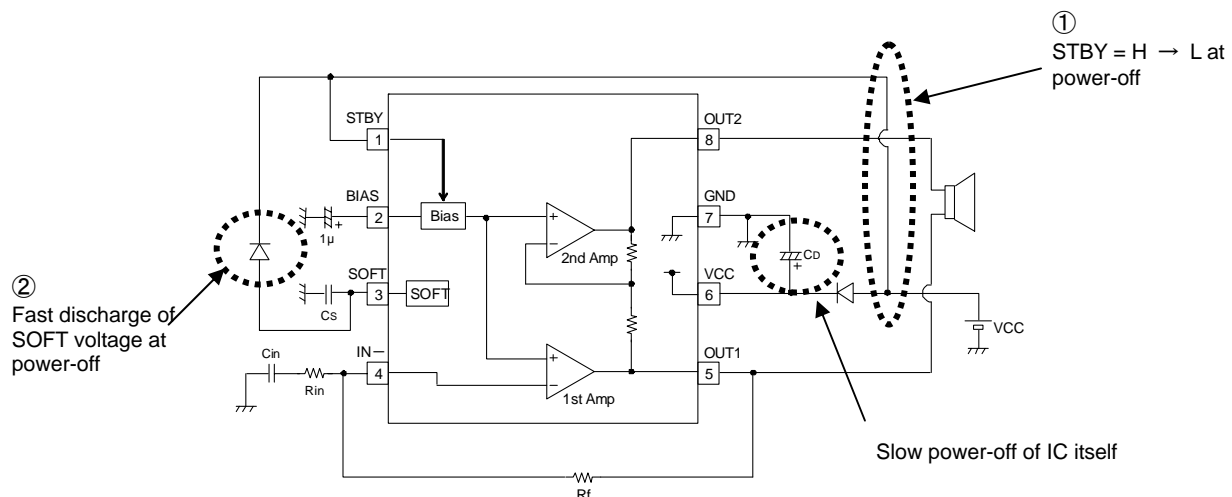
### ● Use when VCC = STBY short

Since this IC is designed on the assumption that it will be used to switch standby mode ON and OFF while the power supply remains ON, normally STBY should be switched from H to L and the SOFT voltage should be discharged before powering down. When used while VCC = STBY short, pop sounds may occur if the IC's power supply is reduced prior to discharging the SOFT voltage.

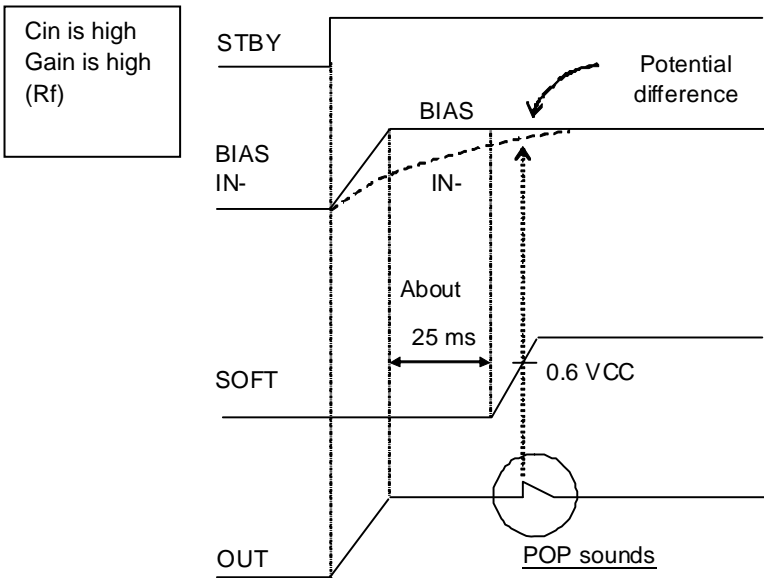
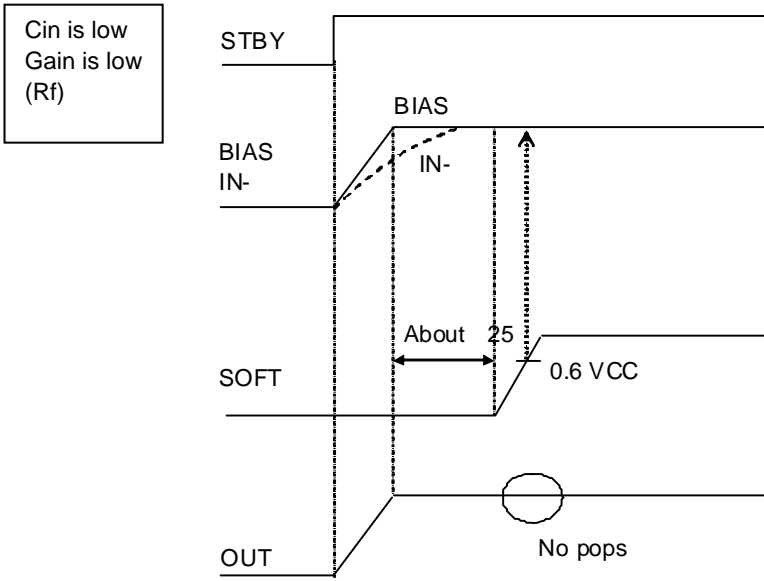
To prevent pop sounds, you must ① set STBY = H → L before setting VCC = H → L, and ② forcibly discharge the SOFT voltage.

A sample circuit in which VCC = STBY short is used is shown below.

- Sample circuit configuration when VCC = STBY short



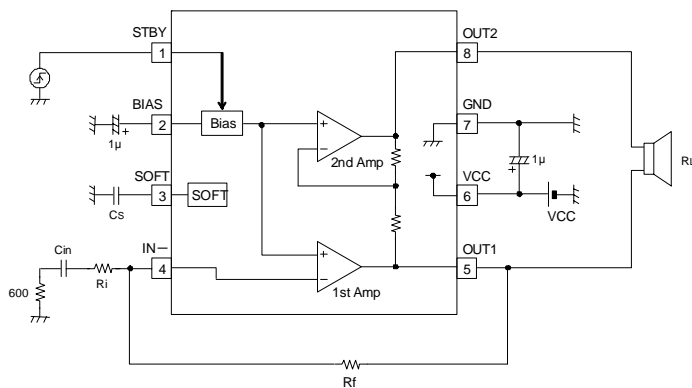
●Mechanism of pop sounds



When SOFT voltage reaches 0.6 VCC, if there is a potential difference between BIAS and IN-, pop sounds will occur.

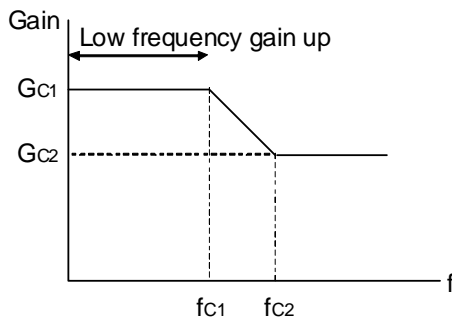
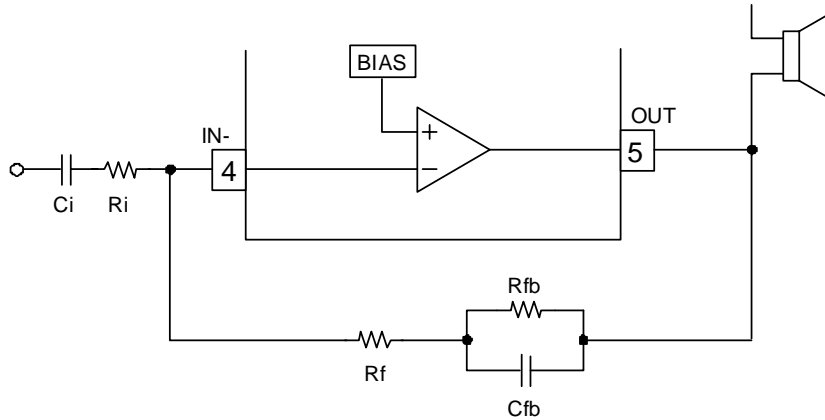
At startup, the input coupling  $C_{in}$  is charged from output OUT via the feedback resistance  $R_f$ , so when  $C_{in}$  and  $R_f$  are high, charging takes longer and pop sounds can easily occur.

The rise of the SOFT voltage is changed by  $C_s$ , so pop sounds can be reduced by setting  $C_s$  high.



● **Bass boost function**

External components can be added to this chip to provide a bass boost function.



$$f_{C2} = \frac{1}{2\pi * C_{fb} * R_f} \quad [\text{Hz}]$$

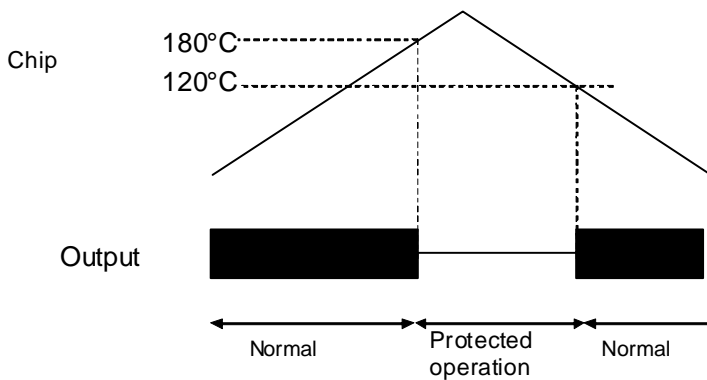
$$f_{C1} = \frac{1}{2\pi * C_{fb} * (R_f // R_{fb})} \quad [\text{Hz}]$$

$$G_{C1} = 20 \log \frac{R_f + R_{fb}}{R_i} \quad [\text{dB}]$$

$$G_{C2} = 20 \log \frac{R_f}{R_i} \text{ (normal use)} \quad [\text{dB}]$$

● **Thermal shutdown function**

When the chip exceeds the Tjmax (150°C) temperature by reaching a temperature of 180°C or above, the protection function is activated. High impedance is for OUT1 and OUT2 during protected mode. Protection is canceled and normal operation is resumed when the chip's temperature falls to 120°C or below.



Protection start temperature: 180°C (typ) or more  
 Protection cancels temperature: 120°C (typ) or less

●Thermal design of chip

The characteristics of the IC vary greatly depending on the use temperature, and when the maximum allowable junction temperature is exceeded, components may deteriorate or become damaged. Thermal considerations are needed for this chip from two standpoints: preventing instantaneous damage and improving long-term reliability. Note the following points with caution.

The absolute maximum ratings for each chip include the maximum junction temperature ( $T_{jMAX}$ ) and operating temperature rate ( $T_{opr}$ ), and these values should be referred to when using the Pd-Ta characteristics (thermal dissipation curve).

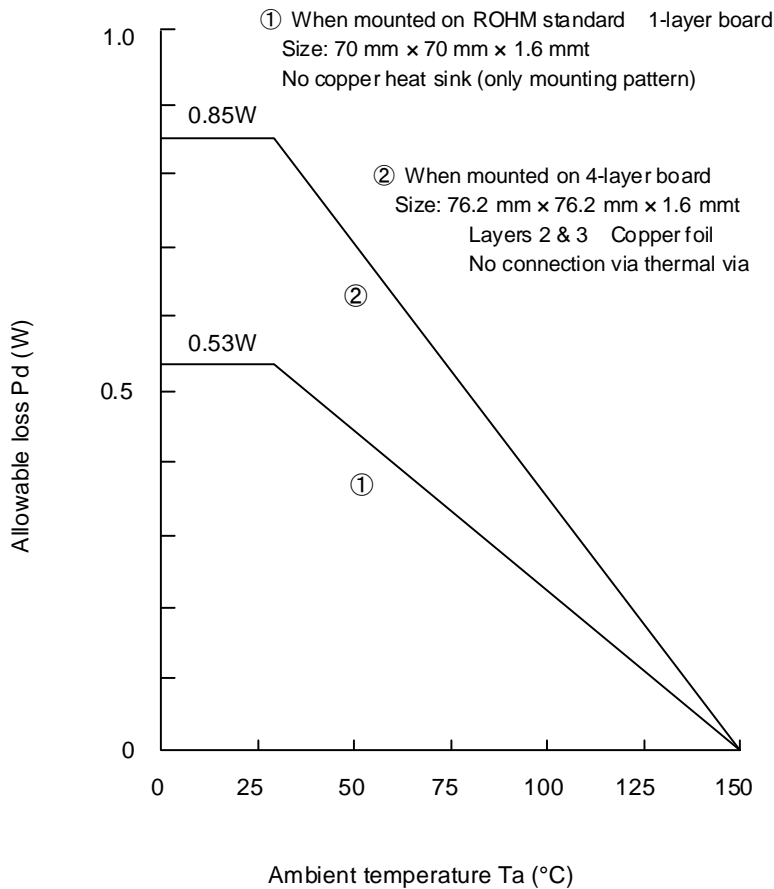
Since the IC itself is designed with full consideration of thermal balance, there are no problems in terms of circuit operations, but even when a more-than-adequate thermal design is implemented in order to get full use of the IC's performance features, some moderation is often required for the sake of practical usage.

If there is an excessive input signal due to insufficient thermal dissipation, a TSD (thermal shutdown) operation may occur.

Thermal Dissipation Curve

Reference data

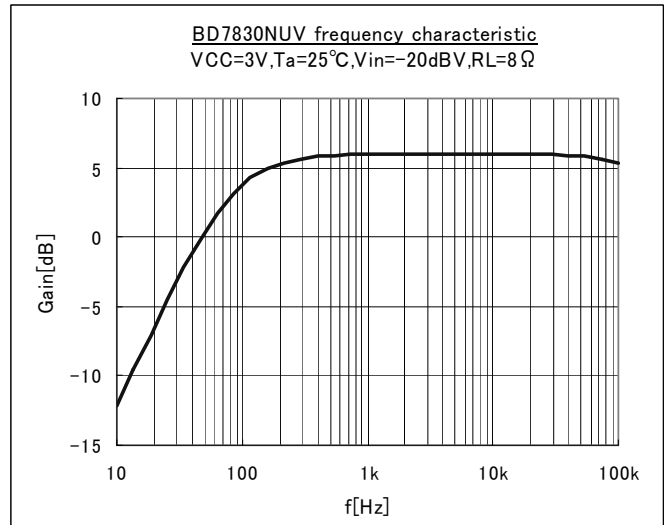
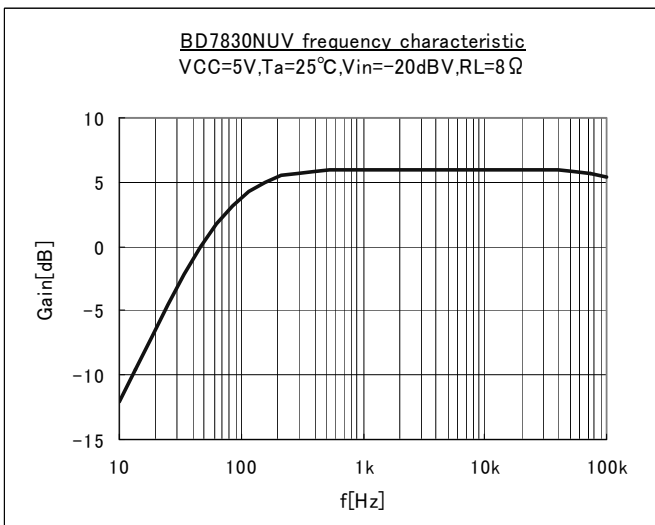
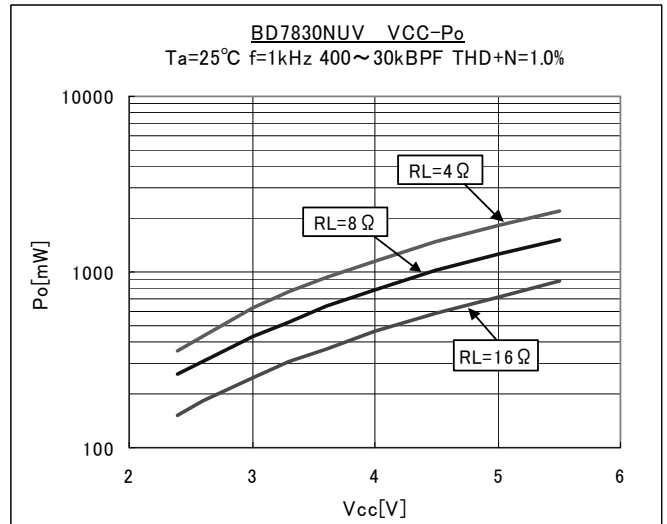
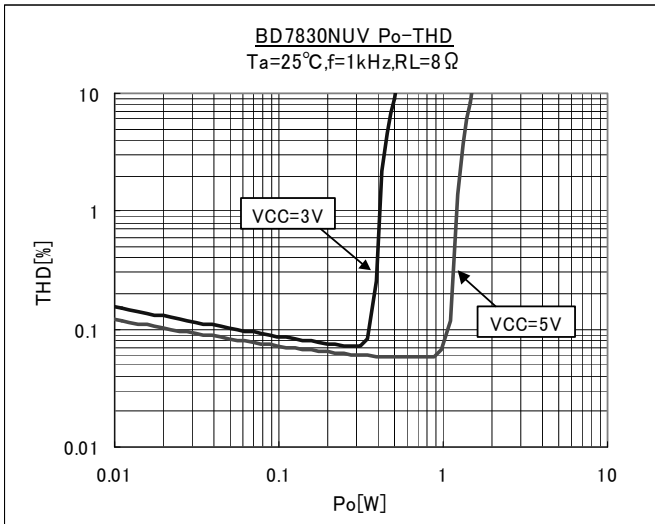
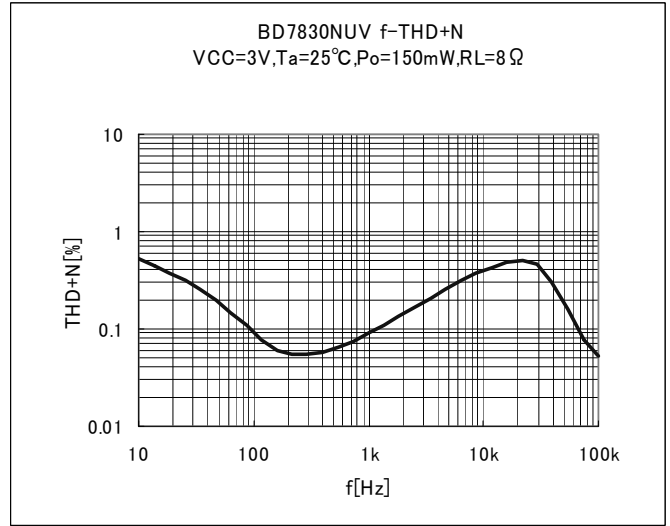
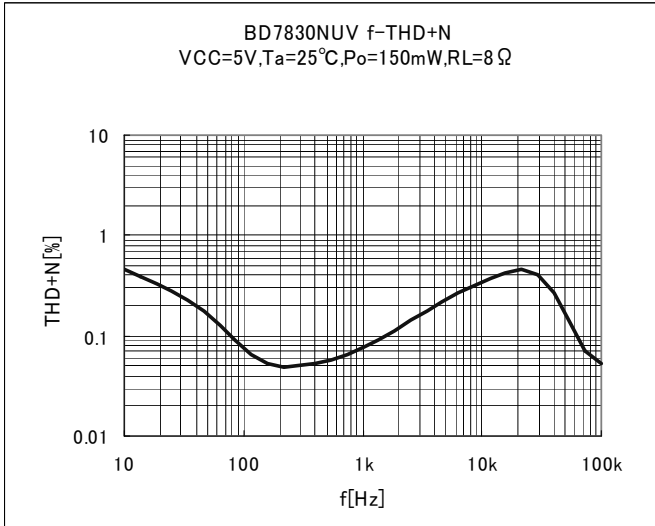
VSON008V2030



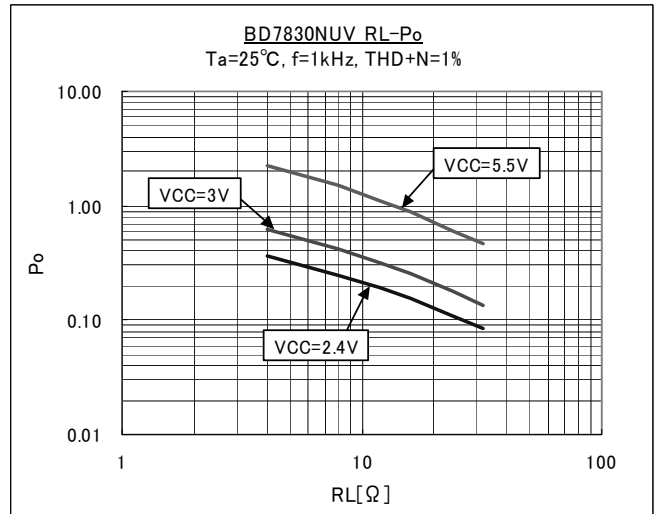
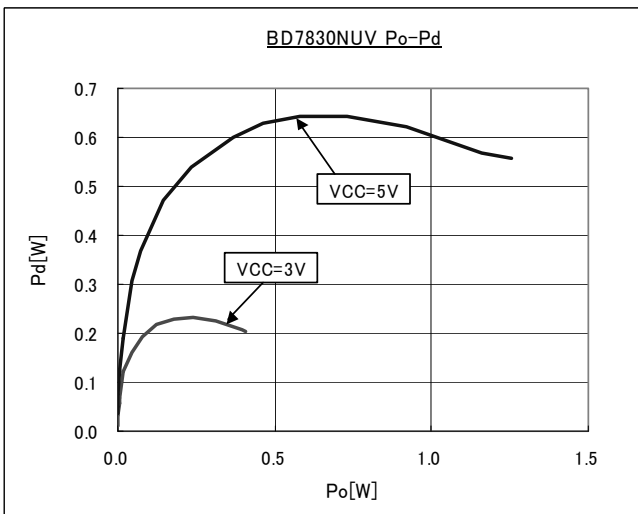
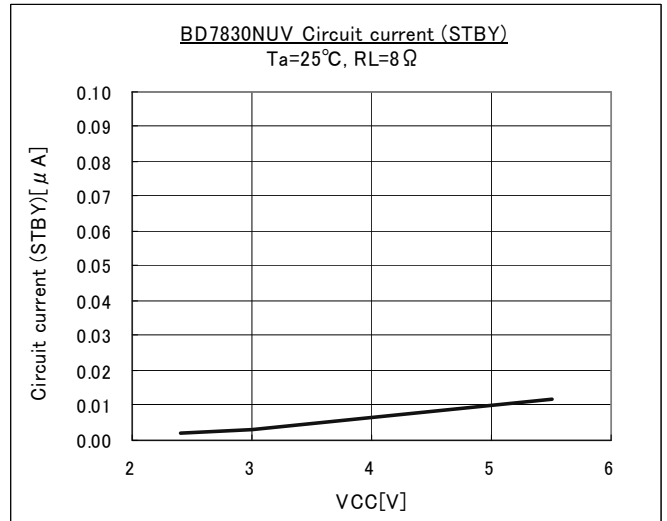
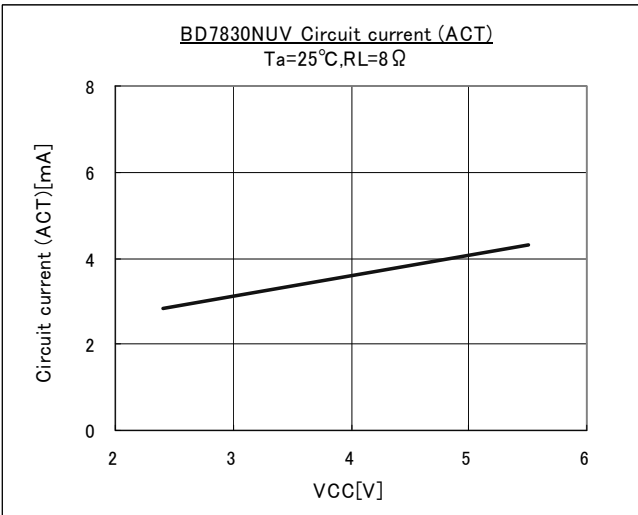
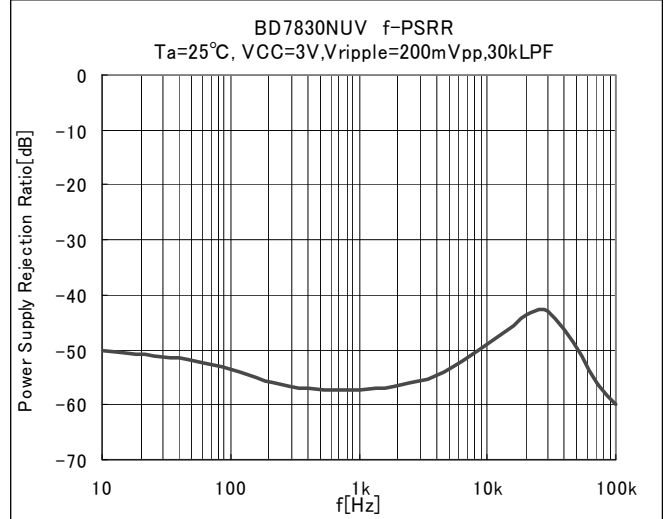
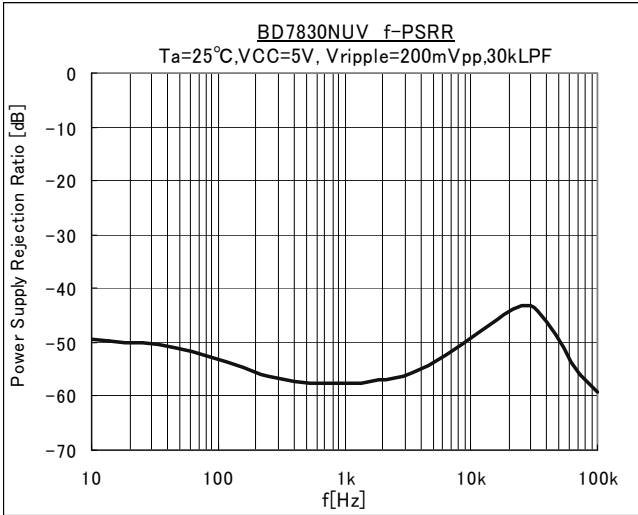
(Note) These are measured values. They are not guaranteed.

The allowable loss value varies depending on the type of board used for mounting. When this chip is mounted on a multi-layer board that is designed for thermal dissipation, the allowable loss becomes greater than shown in the above figure.

● Typical Characteristics (1)



● Typical Characteristics (2)

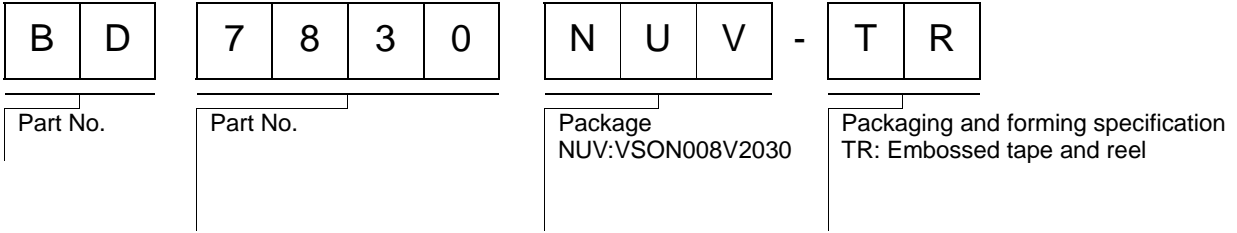


## ●Notes for use

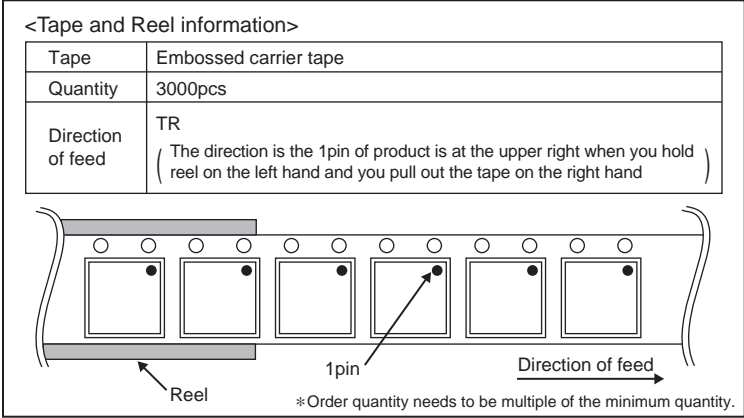
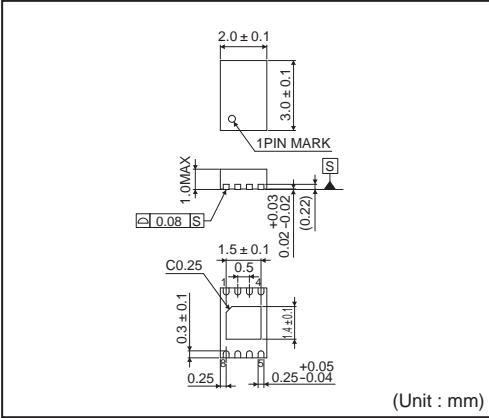
- 1) The above numerical values and data are typical values for the design, which are not guaranteed.
- 2) The application circuit examples can be reliably recommended, but their characteristics should be checked carefully before use. When using external component constants that have been modified, determine an ample margin that takes into consideration variation among the external components and Rohm's LSI IC chips, including variation in static characteristics and transient characteristics.
- 3) Absolute maximum ratings  
This IC may be damaged if the absolute maximum ratings for the applied voltage, temperature range, or other parameters are exceeded. Therefore, avoid using a voltage or temperature that exceeds the absolute maximum ratings. If it is possible that absolute maximum ratings will be exceeded, use fuses or other physical safety measures and determine ways to avoid exceeding the IC's absolute maximum ratings. The above numerical values and data are typical values for the design, which are not guaranteed.
- 4) GND pin's potential  
Try to set the minimum voltage for GND pin's potential, regardless of the operation mode.  
Check that the voltage of each pin does not go below GND pin's voltage, including transient phenomena.
- 5) Shorting between pins and mounting errors  
When mounting the IC chip on a board, be very careful to set the chip's orientation and position precisely. When the power is turned on, the IC may be damaged if it is not mounted correctly. The IC may also be damaged if a short occurs (due to a foreign object, etc.) between two pins, between a pin and the power supply, or between a pin and the GND.
- 6) Shorting output pin  
When output pin (5,8pin) is shorted to VCC or GND, the IC may be damaged by over current, so be careful in operation.
- 7) Thermal design  
Ensure sufficient margins to the thermal design by taking in to account the allowable power dissipation during actual use modes, because this IC is power amp.  
When excessive signal inputs which the heat dissipation is insufficient condition, it is possible that TSD (thermal shutdown circuit) is active.  
TSD is protection of the heat by excessive signal inputs, it is not protection of the shorting output to VCC or GND.
- 8) Shorted pins and mounting errors  
When the output pins (pins 5 and 8) are connected to VCC and GND, the thermal shutdown function repeatedly switches between shutdown (OFF) and cancel (ON). Note with caution that chip damage may occur if these connections remain for a long time.
- 9) Operating range  
The rated operating power supply voltage range(VCC=+2.4 ~ +5.5V) and the rated operation temperature range (Ta=-40~+85°C) are the range by which basic circuit functions is operated.  
It is not guaranteed a specification and a rated output power about all operating power supply voltage range or operation temperature range.
- 10) Operation in strong magnetic fields  
Note with caution that operation faults may occur when this IC operates in a strong magnetic field.



● Ordering part number



VSON008V2030



# Notice

## Precaution on using ROHM Products

- Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment <sup>(Note 1)</sup>, transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASS III	CLASS III	CLASS II b	CLASS III
CLASS IV		CLASS III	

- ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
  - Installation of protection circuits or other protective devices to improve system safety
  - Installation of redundant circuits to reduce the impact of single or multiple circuit failure
- Our Products are designed and manufactured for use under standard conditions and not under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc. prior to use, must be necessary:
  - Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
  - Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - Sealing or coating our Products with resin or other coating materials
  - Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - Use of the Products in places subject to dew condensation
- The Products are not subject to radiation-proof design.
- Please verify and confirm characteristics of the final or mounted products in using the Products.
- In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

## Precaution for Mounting / Circuit board design

- When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- In principle, the reflow soldering method must be used; if flow soldering method is preferred, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

**Precautions Regarding Application Examples and External Circuits**

1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

**Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of ionizer, friction prevention and temperature / humidity control).

**Precaution for Storage / Transportation**

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

**Precaution for Product Label**

QR code printed on ROHM Products label is for ROHM's internal use only.

**Precaution for Disposition**

When disposing Products please dispose them properly using an authorized industry waste company.

**Precaution for Foreign Exchange and Foreign Trade act**

Since our Products might fall under controlled goods prescribed by the applicable foreign exchange and foreign trade act, please consult with ROHM representative in case of export.

**Precaution Regarding Intellectual Property Rights**

1. All information and data including but not limited to application example contained in this document is for reference only. ROHM does not warrant that foregoing information or data will not infringe any intellectual property rights or any other rights of any third party regarding such information or data. ROHM shall not be in any way responsible or liable for infringement of any intellectual property rights or other damages arising from use of such information or data.:
2. No license, expressly or implied, is granted hereby under any intellectual property rights or other rights of ROHM or any third parties with respect to the information contained in this document.

**Other Precaution**

1. This document may not be reprinted or reproduced, in whole or in part, without prior written consent of ROHM.
2. The Products may not be disassembled, converted, modified, reproduced or otherwise changed without prior written consent of ROHM.
3. In no event shall you use in any way whatsoever the Products and the related technical information contained in the Products or this document for any military purposes, including but not limited to, the development of mass-destruction weapons.
4. The proper names of companies or products described in this document are trademarks or registered trademarks of ROHM, its affiliated companies or third parties.

**General Precaution**

1. Before you use our Products, you are requested to carefully read this document and fully understand its contents. ROHM shall not be in any way responsible or liable for failure, malfunction or accident arising from the use of any ROHM's Products against warning, caution or note contained in this document.
2. All information contained in this document is current as of the issuing date and subject to change without any prior notice. Before purchasing or using ROHM's Products, please confirm the latest information with a ROHM sales representative.
3. The information contained in this document is provided on an "as is" basis and ROHM does not warrant that all information contained in this document is accurate and/or error-free. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties resulting from inaccuracy or errors of or concerning such information.